Hybrid 8j238 Traveler

February 15, 2000

1 Connectivity

Repairs on shorts:

Fixes for opens:

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 8J238 has die: 000-000 000-000 000-000 000-000 000-000 000-000 000-000 000-000

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

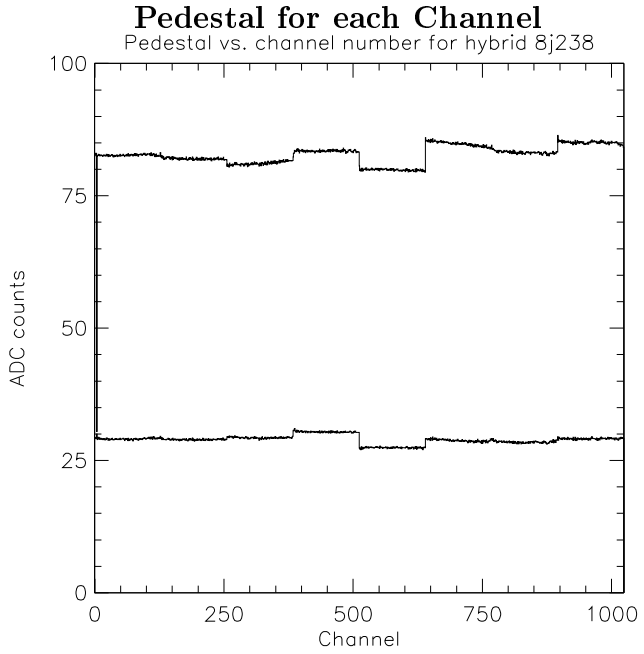
```
% Hybrid 8j238 classification info. Created 10:57:59 02/14/00

Hybrid 8j238 quality: bad
Chip classification: fair good good bad good good good good
Bad channels (chip-channel): 0-4 3-109 3-111 3-112
Bad cells: none
Random bad capacitors (chip-cell-channel): 3-16-110 3-16-111 3-17-111
   3-20-110 3-20-111 3-21-111 3-23-110 3-23-111 3-25-110 3-25-111 3-27-110
   3-27-111 3-3-110 3-3-111 3-36-110 3-36-111 3-37-111
Channels at pedestal needed for DCMS: 33.6 29.7 30.6 30.7 36.6 33.8 31.7 31.5
```

4 Comments

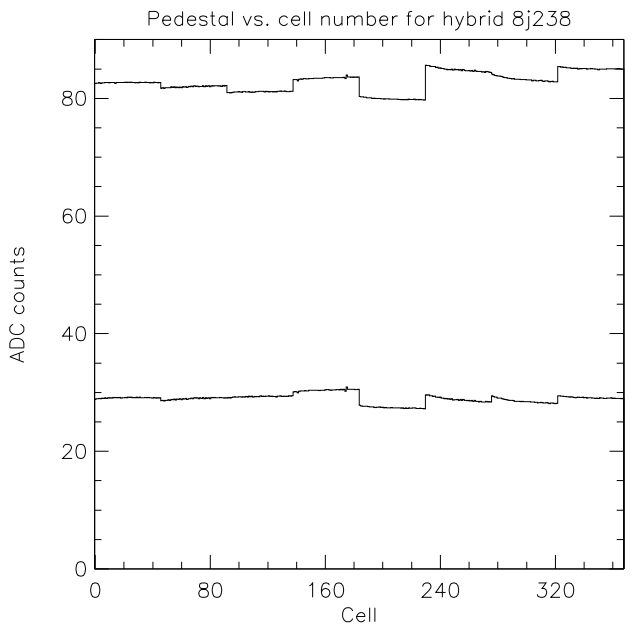
Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

The following plot shows the pedestals vs. channel number with and without charge injection:



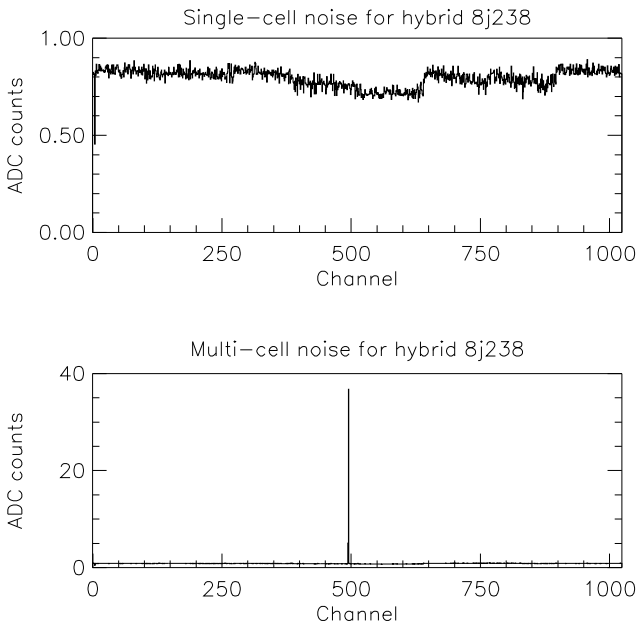
The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.



6 Noise

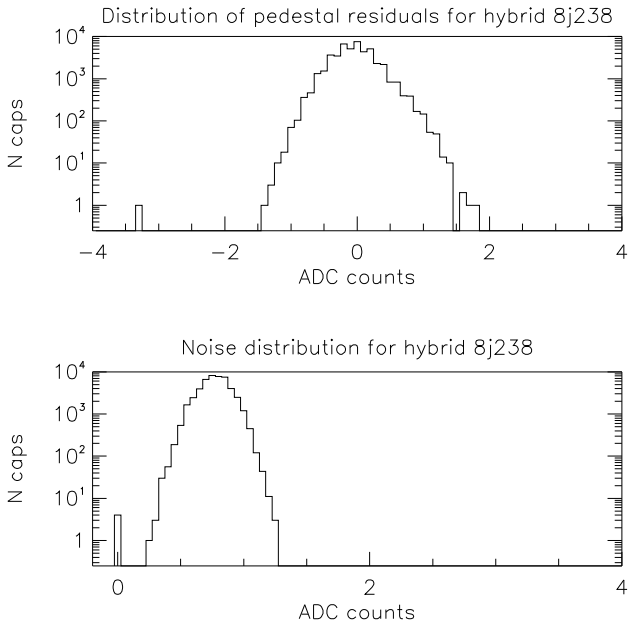
The following plots show the single-cell and multi-cell RMS noise:

RMS Noise

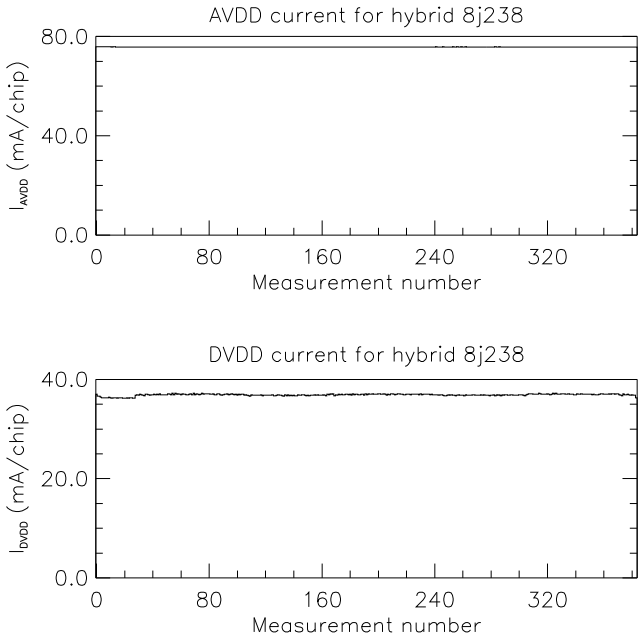


The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise



7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in